

**SN74ALVCHS162830**  
**1-BIT TO 2-BIT ADDRESS DRIVER**  
**WITH 3-STATE OUTPUTS**  
 SCES097F – APRIL 1997 – REVISED JUNE 1999

- Member of the Texas Instruments *Widebus™* Family
- *EPIC™* (Enhanced-Performance Implanted CMOS) Submicron Process
- Output Ports Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required
- Diodes on Inputs Clamp Overshoot
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Packaged in Thin Very Small-Outline Package

NOTE: For order entry:  
 The DBB package is abbreviated to G.

For tape and reel:  
 The DBBR package is abbreviated to GR.

**description**

This 1-bit to 2-bit address driver is designed for 2.3-V to 3.6-V  $V_{CC}$  operation.

Diodes to  $V_{CC}$  have been added on the inputs to clamp overshoot.

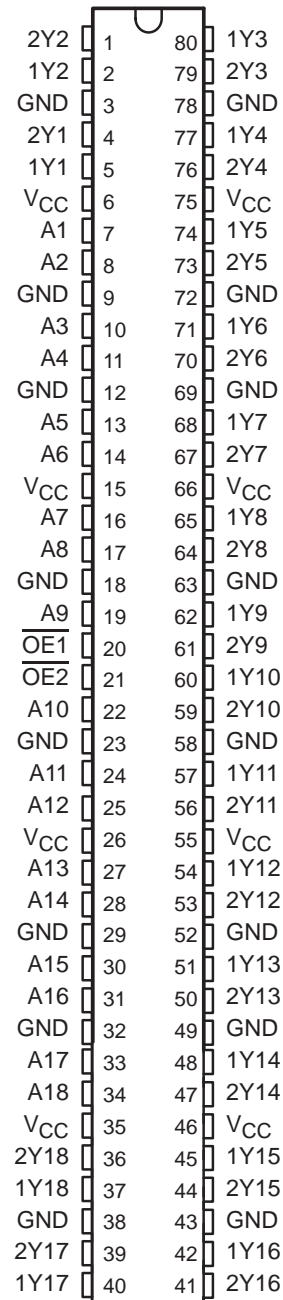
Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The outputs, which are designed to sink up to 12 mA, include equivalent 26-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, the output-enable (OE) input should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ALVCHS162830 is characterized for operation from -40°C to 85°C.

**DBB PACKAGE**  
**(TOP VIEW)**



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# SN74ALVCHS162830

## 1-BIT TO 2-BIT ADDRESS DRIVER

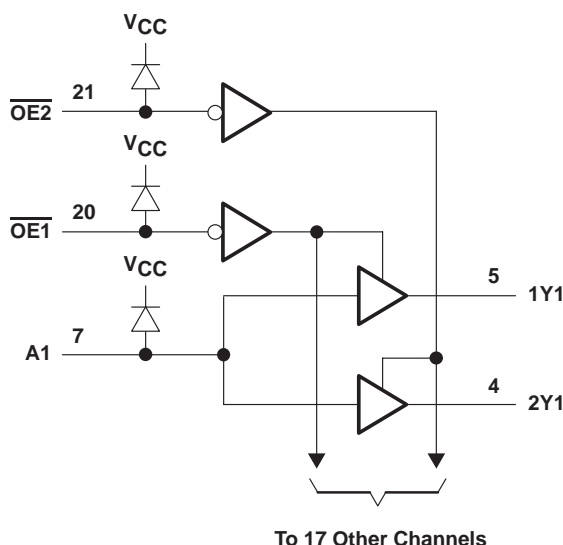
### WITH 3-STATE OUTPUTS

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FUNCTION TABLE

INPUTS			OUTPUTS	
$\overline{OE1}$	$\overline{OE2}$	A	1Yn	2Yn
L	H	H	H	Z
L	H	L	L	Z
H	L	H	Z	H
H	L	L	Z	L
L	L	H	H	H
L	L	L	L	L
H	H	X	Z	Z

#### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	-0.5 V to 4.6 V
Input voltage range, $V_I$ (see Note 1)	-0.5 V to 4.6 V
Output voltage range, $V_O$ (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	-50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	-50 mA
Continuous output current, $I_O$	$\pm 50$ mA
Continuous current through each $V_{CC}$ or GND	$\pm 100$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 3)	106°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
  2. This value is limited to 4.6 V maximum.
  3. The package thermal impedance is calculated in accordance with JESD 51.



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**recommended operating conditions (see Note 4)**

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2.3	3.6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	2	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	0.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	0.8	
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2.3 V	-6	mA
		V <sub>CC</sub> = 2.7 V	-8	
		V <sub>CC</sub> = 3 V	-12	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.3 V	6	mA
		V <sub>CC</sub> = 2.7 V	8	
		V <sub>CC</sub> = 3 V	12	
Δt/Δv	Input transition rise or fall rate		10	ns/V
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP†	MAX	UNIT
V <sub>IK</sub>		I <sub>I</sub> = -18 mA	2.3 V			-1.2	V
		I <sub>I</sub> = 18 mA	2.3 V			V <sub>CC</sub> +1.2	
V <sub>OH</sub>		I <sub>OH</sub> = -100 μA	2.3 V to 3.6 V	V <sub>CC</sub> -0.2			V
		I <sub>OH</sub> = -4 mA, V <sub>IH</sub> = 1.7 V	2.3 V	1.9			
		I <sub>OH</sub> = -6 mA	V <sub>IH</sub> = 1.7 V	2.3 V		1.7	
			V <sub>IH</sub> = 2 V	3 V		2.4	
		I <sub>OH</sub> = -8 mA, V <sub>IH</sub> = 2 V	2.7 V	2			
	I <sub>OH</sub> = -12 mA, V <sub>IH</sub> = 2 V	3 V	2				
V <sub>OL</sub>		I <sub>OL</sub> = 100 μA	2.3 V to 3.6 V			0.2	V
		I <sub>OL</sub> = 4 mA, V <sub>IL</sub> = 0.7 V	2.3 V			0.4	
		I <sub>OL</sub> = 6 mA	V <sub>IL</sub> = 0.7 V	2.3 V		0.55	
			V <sub>IL</sub> = 0.8 V	3 V		0.55	
		I <sub>OL</sub> = 8 mA, V <sub>IL</sub> = 0.8 V	2.7 V			0.6	
	I <sub>OL</sub> = 12 mA, V <sub>IL</sub> = 0.8 V	3 V			0.8		
I <sub>I</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V			±5	μA
I <sub>I</sub> (hold)		V <sub>I</sub> = 0.7 V	2.3 V	45			μA
		V <sub>I</sub> = 1.7 V	2.3 V	-45			
		V <sub>I</sub> = 0.8 V	3 V	75			
		V <sub>I</sub> = 2 V	3 V	-75			
		V <sub>I</sub> = 0 to 3.6 V‡	3.6 V			±500	
I <sub>OZ</sub>		V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V			±10	μA
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V			40	μA
ΔI <sub>CC</sub>		One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V			750	μA
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	5.5			pF
	Data inputs			7			
C <sub>o</sub>	Outputs	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V	7.5			pF

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

**switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	1.2	3.8	4		1.7	3.5	ns
t <sub>en</sub>	$\overline{\text{OE}}$	Y	1	5.7	5.7		1	4.8	ns
t <sub>dis</sub>	$\overline{\text{OE}}$	Y	1	4.9	5.4		1.7	5.2	ns

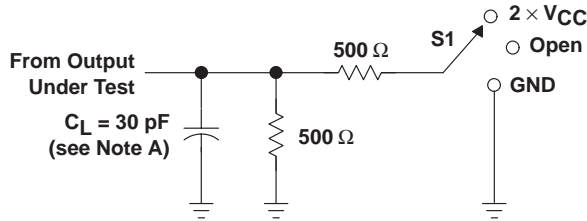
**operating characteristics, T<sub>A</sub> = 25°C**

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			TYP	TYP	TYP	TYP	
C <sub>pd</sub>	Power dissipation capacitance per driver	All outputs enabled	C <sub>L</sub> = 0, f = 10 MHz	49	53	pF	
		All outputs disabled		6	7.5		



**PARAMETER MEASUREMENT INFORMATION**

$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

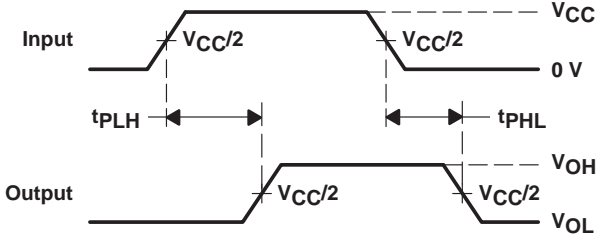


**LOAD CIRCUIT**

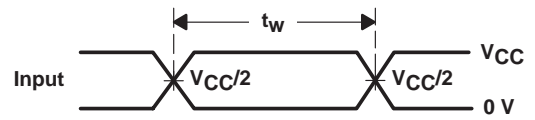
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND



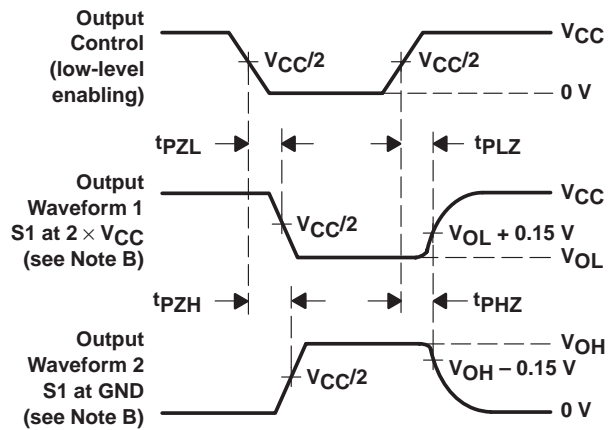
**VOLTAGE WAVEFORMS  
 SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS  
 PROPAGATION DELAY TIMES**



**VOLTAGE WAVEFORMS  
 PULSE DURATION**



**VOLTAGE WAVEFORMS  
 ENABLE AND DISABLE TIMES**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 2\text{ ns}$ ,  $t_f \leq 2\text{ ns}$ .  
 D. The outputs are measured one at a time with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

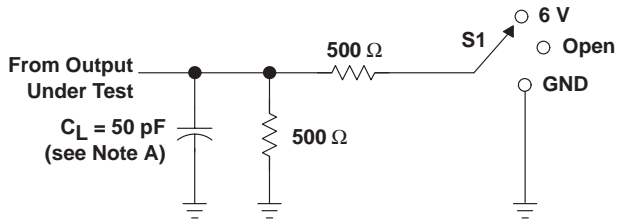
**Figure 1. Load Circuit and Voltage Waveforms**

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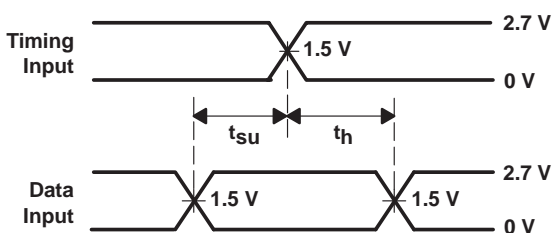
**PARAMETER MEASUREMENT INFORMATION**

$V_{CC} = 2.7\text{ V AND } 3.3\text{ V} \pm 0.3\text{ V}$

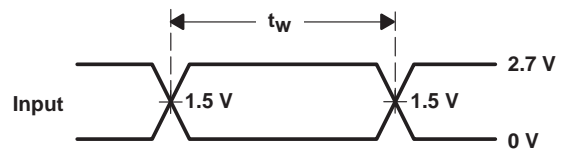


**LOAD CIRCUIT**

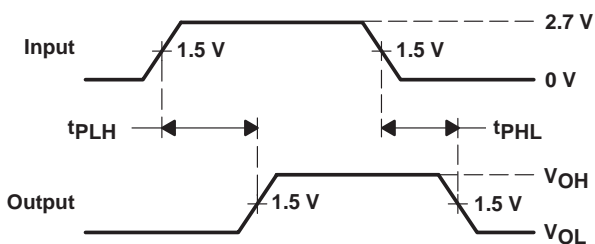
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND



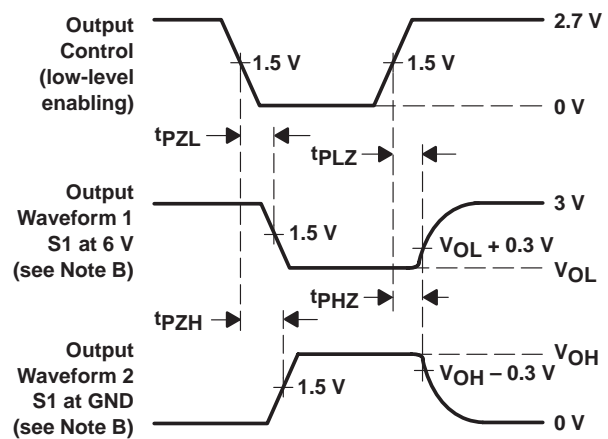
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 PROPAGATION DELAY TIMES**



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 D. The outputs are measured one at a time with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

**Figure 2. Load Circuit and Voltage Waveforms**

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